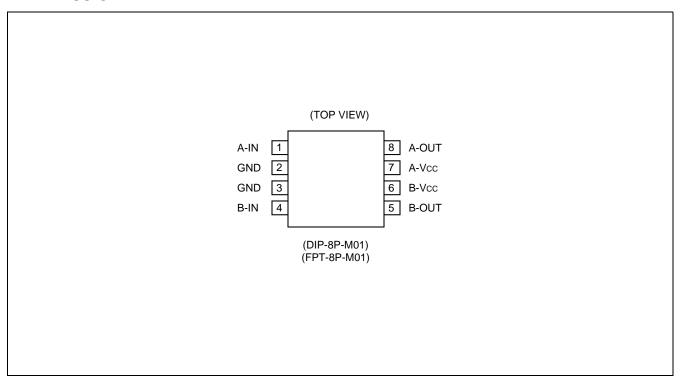
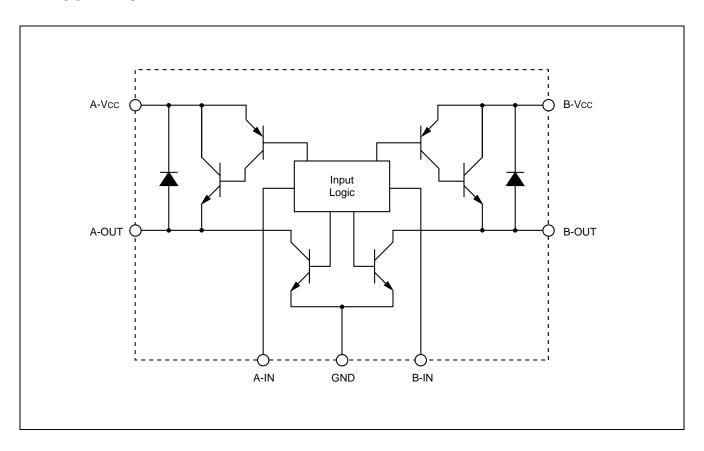
■ PIN ASSIGNMENT



■ BLOCK DIAGRAM



■ ABSOLUTE MAXIMUM RATINGS

 $(Ta = +25^{\circ}C)$

Parameter	Symbol	Rating		
raiailletei		Min.	Max.	Unit
Power supply voltage	Vcc	_	20	V
Output current	lo	-	180 (330*1)	mA
Maximum output current	IOMAX*3	_	1.2	Α
Power Dissipation	Po	_	560* ²	mW
Operating temperature	Tc	-20	+75	°C
Storage temperature	Tstg	– 55	+125	°C

^{*1:} $ton \le 1 s$, Duty = 50%

WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

■ RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Va	Unit	
Farameter	Symbol	Min.	Max.	Onit
Power supply voltage	Vcc	4	18	V
Output current	lo	0	150 (300*1)	mA
Input high voltage	VIH*2	2.4	Vcc + 0.3	V
Input low voltage	VIL	0	0.4	V

^{*1:} $ton \le 1 s$, Duty = 50%

WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their representatives beforehand.

^{*2:} Ta \leq 60°C *3: t \leq 5 ms

^{*2:} When $V_{IH} \ge V_{CC}$, $I_{IH} \le V_{CC} \times 0.2$ mA

■ ELECTRICAL CHARACTERISTICS

(Vcc = 12 V, Ta = +25°C)

Parameter	Symbol	Condition	Value			Unit
Parameter		Condition	Min.	Тур.	Max.	Oill
Standby supply current	Icco	Vcc = 18 V, VIA = VIB = 0 V	_	_	1.0	mA
	Icc1	Io = 0 mA	_	10	20	mA
Power supply current	Icc2	Io = 150 mA	_	10	_	mA
		Io = 300 mA	_	15	_	mA
	Іссз	Io = 0 mA, VIA = VIB = 2.4 V	_	15	_	mA
Output high voltage	Vон	Io = 150 mA	11.0	11.2	_	V
		Io = 300 mA	10.8	11.1	_	V
Output low voltage	Vol	Io = 150 mA	_	0.1	0.2	V
Output low voltage		Io = 300 mA	_	0.2	0.5	V
Outrout actions valte as	Vsat	Io = 150 mA	_	0.9	1.2	V
Output saturation voltage		Io = 300 mA	_	1.1	1.7	V
Input current	Іін	Vin = 2.4 V	_	250	400	μΑ
Input switching prohibition time	Toff	_	10	_	_	μS

■ FUNCTIONAL DESCRIPTIONS

FORWARD/REVERSE MODE (MODE B& C)

In this mode, the transistor pairs Q2-Q3 and Q1-Q4 work alternatively, changing the output current direction. When the mode B is selected, Q2 and Q3 are active and Q1 and Q4 are inactive. Therefore A-OUT is at low level and B-OUT is at high level, with the current flowing from B-OUT to A-OUT through the motor. On the other hand, when the mode C is selected, the current flows in the reverse direction.

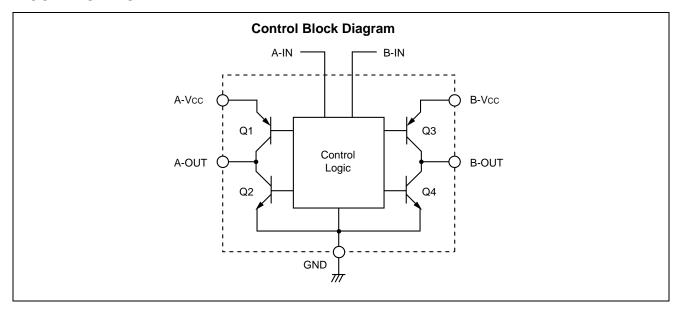
BRAKE/STOP MODE (MODE A)

When the mode A is selected, Q1 and Q3 are inactive and Q2 and Q4 are active. A-OUT and B-OUT are stuck at low-level; terminals of motor are shorted and the motor is forced to stop.

STANDBY MODE (MODE D)

In this mode, all transistors are inactive and the current through the motor does not flow. When the power supply voltage is applied to A-Vcc and B-Vcc, the supply current is still less than or equal to 1 mA.

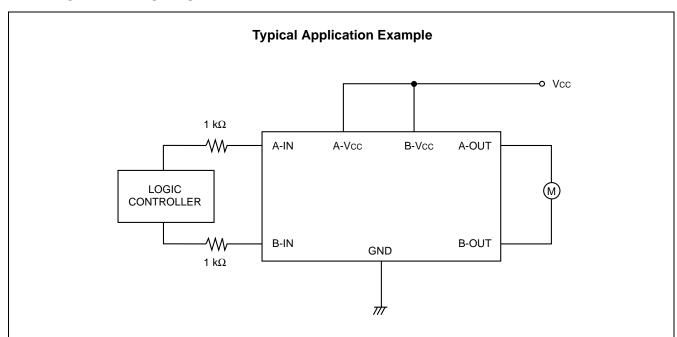
■ CONTROL MODE



Mode	Input mode		Output mode		Operation
Iviode	A-IN	B-IN	A-OUT	B-OUT	- Operation
А	1	1	L	L	short (Brake)
В	1	0	L	Н	Forward
С	0	1	Н	L	Reverse
D	0	0	_	_	Open (Standby)

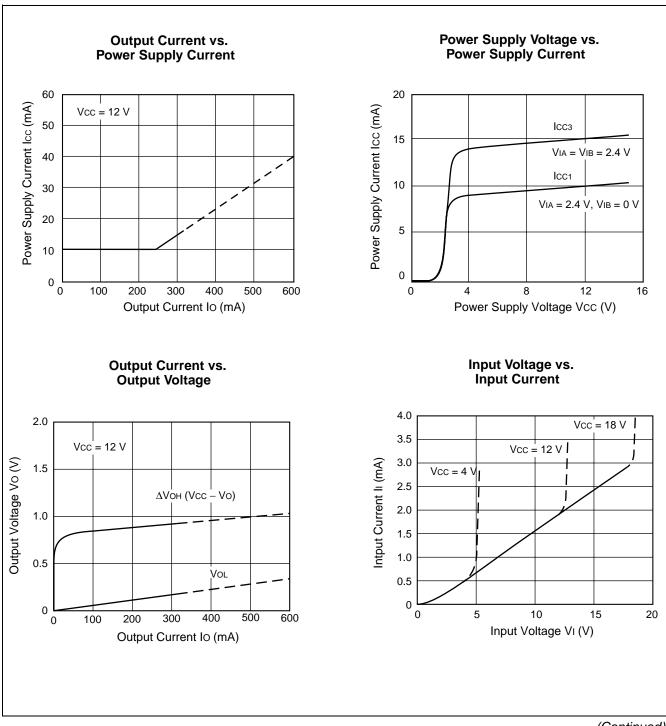
Notes: $1: \ge 2.4V$ $0: \le 0.4V$

■ TYPICAL APPLICATION



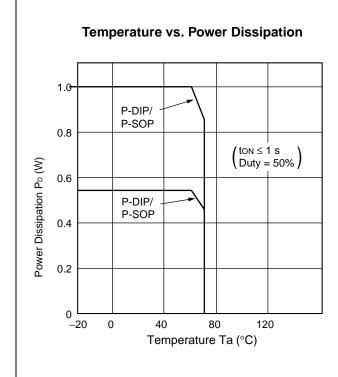
Note: In the case the control voltage is input when the power supply voltage is not applied because of the time lag between those two voltages, excess current flows into IC from the input terminals. In this case, please connect a resistor (\geq 1 k Ω) serially to input pin in order to prevent excess current flow.

■ TYPICAL PERFORMANCE CHARACTERISTICS



(Continued)

(Continued)



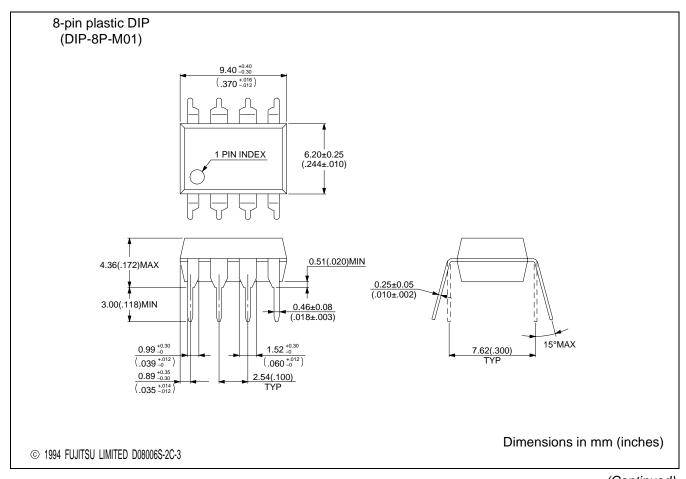
P-SOP's value is measured on the ceramic board (3.0 cm x 3.0 cm x 0.05 cm)

Maximum power dissipation must be kept.

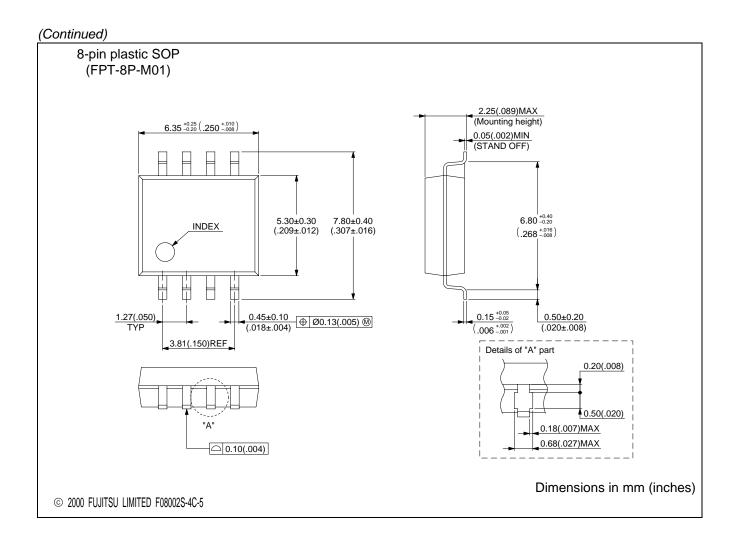
■ ORDERING INFORMATION

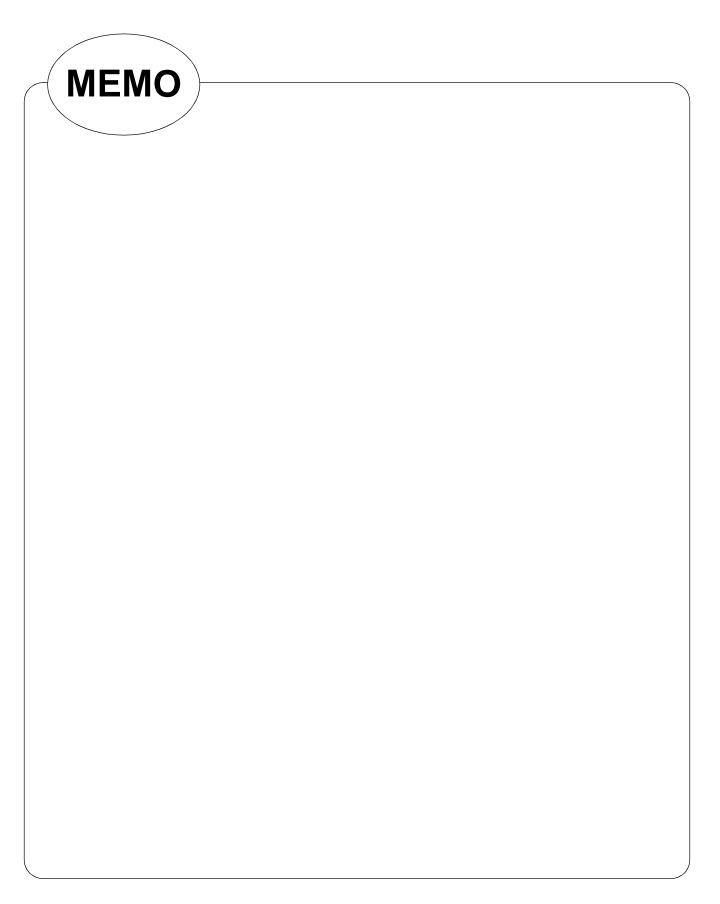
Part number	Package	Remarks	
MB3763	8-pin plastic DIP (DIP-8P-M01)		
MB3763PF	8-pin plastic SOP (FPT-8P-M01)		

■ PACKAGE DIMENSIONS



(Continued)





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